

## 256K x 8 HIGH SPEED ASYNCHRONOUS CMOS STATIC RAM WITH ECC

DECEMBER 2011

### FEATURES

- High-speed access time: 8, 10 ns
- Low Active Power: 85 mW (typical)
- Low Standby Power: 7 mW (typical)  
CMOS standby
- Single power supply
  - $V_{DD}$  2.4V to 3.6V (10 ns)
  - $V_{DD}$  3.3V  $\pm$  10% (8 ns)
- Fully static operation: no clock or refresh required
- Three state outputs
- Industrial and Automotive temperature support
- Lead-free available
- Error Detection and Error Correction

### DESCRIPTION

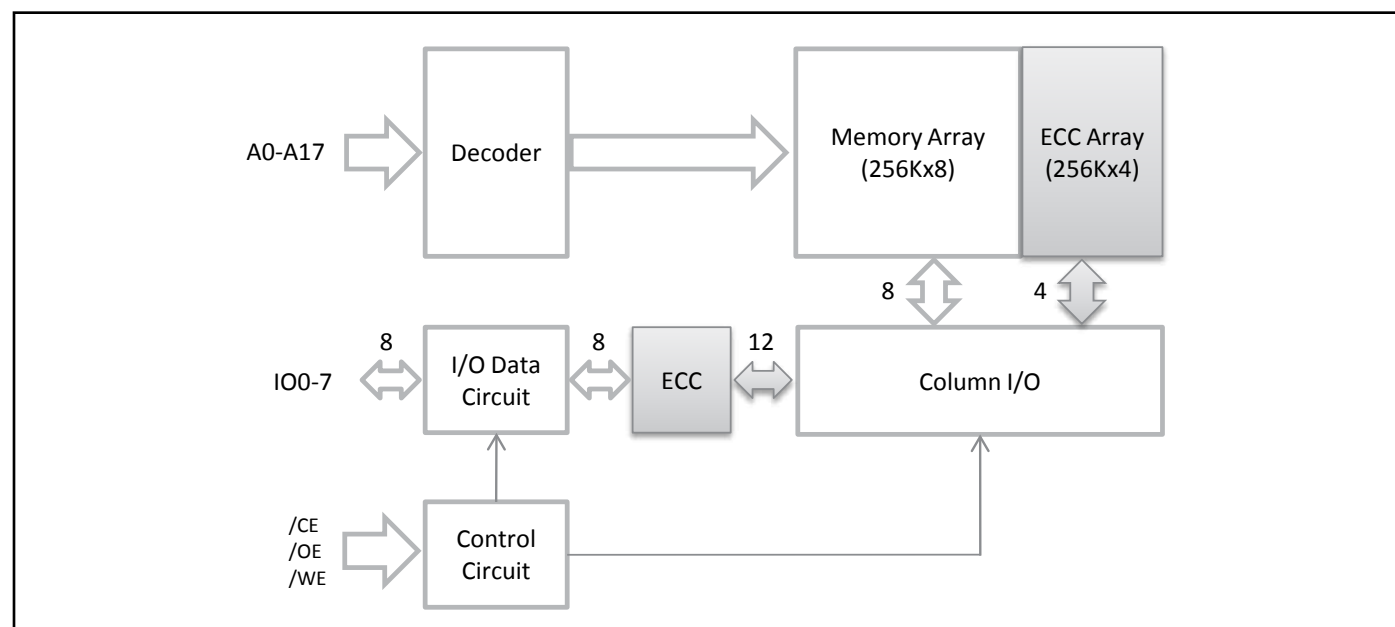
The *ISSI* IS61/64WV2568EDBLL is a high-speed, 2,097,152-bit static RAMs organized as 262,144 words by 8 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When  $\overline{CE}$  is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs,  $\overline{CE}$  and  $\overline{OE}$ . The active LOW Write Enable ( $\overline{WE}$ ) controls both writing and reading of the memory.

The IS61/64WV2568EDBLL is packaged in the JEDEC standard 44-pin TSOP-II, 36-pin SOJ and 36-pin Mini BGA (6mm x 8mm).

### FUNCTIONAL BLOCK DIAGRAM



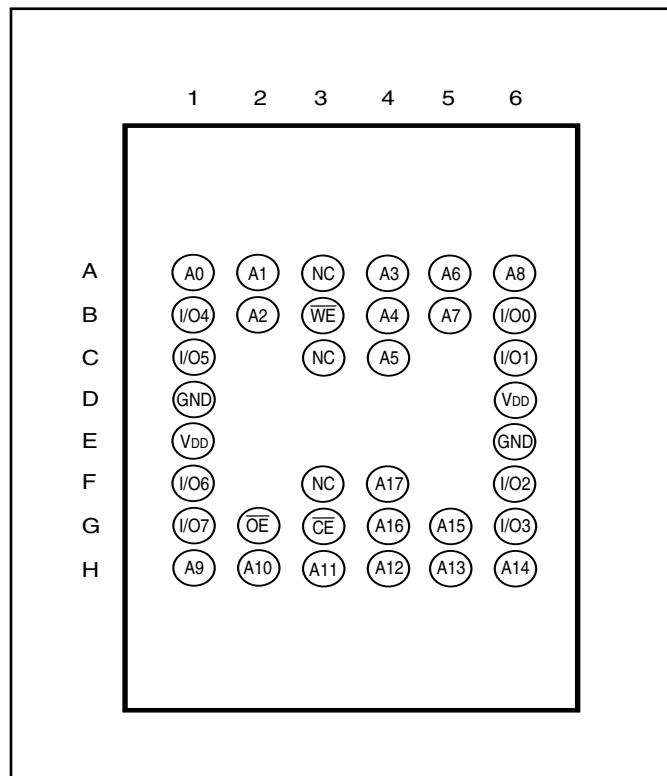
Copyright © 2011 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

Integrated Silicon Solution, Inc. does not recommend the use of any of its products in life support applications where the failure or malfunction of the product can reasonably be expected to cause failure of the life support system or to significantly affect its safety or effectiveness. Products are not authorized for use in such applications unless Integrated Silicon Solution, Inc. receives written assurance to its satisfaction, that:

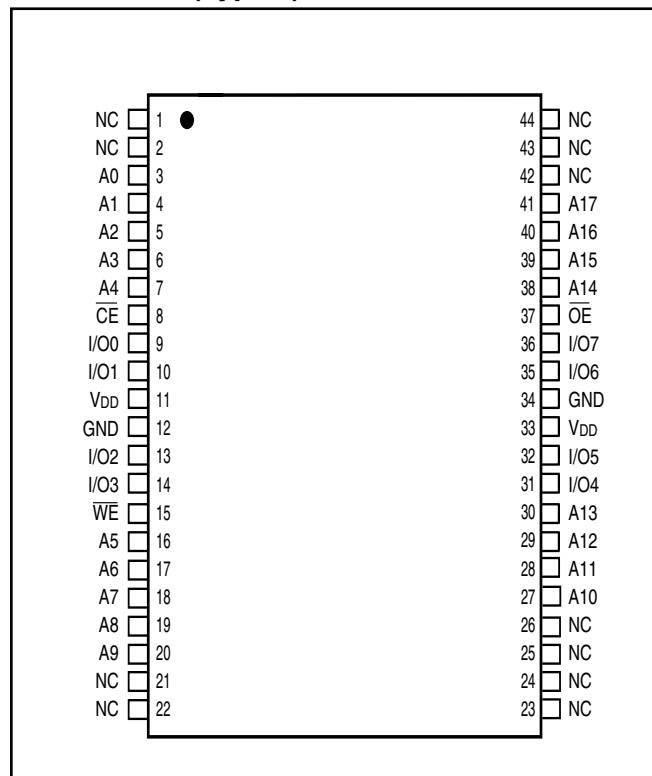
- a.) the risk of injury or damage has been minimized;
- b.) the user assume all such risks; and
- c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

## PIN CONFIGURATION

### 36 mini BGA



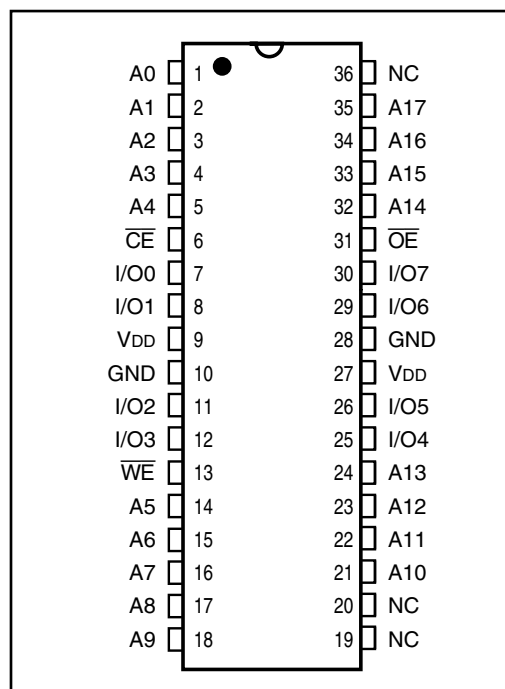
### 44-Pin TSOP (Type II)



## PIN DESCRIPTIONS

|                 |                     |
|-----------------|---------------------|
| A0-A17          | Address Inputs      |
| $\overline{CE}$ | Chip Enable Input   |
| $\overline{OE}$ | Output Enable Input |
| $\overline{WE}$ | Write Enable Input  |
| I/O0-I/O7       | Bidirectional Ports |
| V <sub>DD</sub> | Power               |
| GND             | Ground              |
| NC              | No Connection       |

### 36-Pin SOJ



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol            | Parameter                            | Value                         | Unit |
|-------------------|--------------------------------------|-------------------------------|------|
| V <sub>TERM</sub> | Terminal Voltage with Respect to GND | −0.5 to V <sub>DD</sub> + 0.5 | V    |
| V <sub>DD</sub>   | V <sub>DD</sub> Relates to GND       | −0.3 to 4.0                   | V    |
| T <sub>STG</sub>  | Storage Temperature                  | −65 to +150                   | °C   |
| P <sub>T</sub>    | Power Dissipation                    | 1.0                           | W    |

**Notes:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**CAPACITANCE<sup>(1,2)</sup>**

| Symbol           | Parameter                | Conditions            | Max. | Unit |
|------------------|--------------------------|-----------------------|------|------|
| C <sub>IN</sub>  | Input Capacitance        | V <sub>IN</sub> = 0V  | 6    | pF   |
| C <sub>I/O</sub> | Input/Output Capacitance | V <sub>OUT</sub> = 0V | 8    | pF   |

**Notes:**

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T<sub>A</sub> = 25°C, f = 1 MHz, V<sub>DD</sub> = 3.3V.

**ERROR DETECTION AND ERROR CORRECTION**

- Independent ECC with hamming code for each byte
- Detect and correct one bit error per byte
- Better reliability than parity code schemes which can only detect an error but not correct an error
- Backward Compatible: Drop in replacement to current in industry standard devices (without ECC)

**TRUTH TABLE**

| Mode                         | $\overline{CE}$ | $\overline{WE}$ | $\overline{OE}$ | I/O Operation | V <sub>DD</sub> Current             |
|------------------------------|-----------------|-----------------|-----------------|---------------|-------------------------------------|
| Not Selected<br>(Power-down) | H               | X               | X               | High-Z        | I <sub>SB1</sub> , I <sub>SB2</sub> |
| Output Disabled              | L               | H               | H               | High-Z        | I <sub>CC</sub>                     |
| Read                         | L               | H               | L               | DOUT          | I <sub>CC</sub>                     |
| Write                        | L               | L               | X               | DIN           | I <sub>CC</sub>                     |

**OPERATING RANGE (V<sub>DD</sub>)<sup>1</sup>**

| Range           | Ambient Temperature | IS61WV2568EDBLL<br>V <sub>DD</sub> (8, 10ns) | IS64WV2568EDBLL<br>V <sub>DD</sub> (10ns) |
|-----------------|---------------------|----------------------------------------------|-------------------------------------------|
| Industrial      | −40°C to +85°C      | 2.4V-3.6V (10ns)<br>3.3V ± 10% (8ns)         | —                                         |
| Automotive (A1) | −40°C to +85°C      | —                                            | 2.4V-3.6V                                 |
| Automotive (A3) | −40°C to +125°C     | —                                            | 2.4V-3.6V                                 |

**Note:**

1. Contact SRAM@issi.com for 1.8V option

**DC ELECTRICAL CHARACTERISTICS** (Over Operating Range)**V<sub>DD</sub> = 3.3V ± 10%**

| Symbol          | Parameter                        | Test Conditions                                             | Min. | Max.                  | Unit |
|-----------------|----------------------------------|-------------------------------------------------------------|------|-----------------------|------|
| V <sub>OH</sub> | Output HIGH Voltage              | V <sub>DD</sub> = Min., I <sub>OH</sub> = -4.0 mA           | 2.4  | —                     | V    |
| V <sub>OL</sub> | Output LOW Voltage               | V <sub>DD</sub> = Min., I <sub>OL</sub> = 8.0 mA            | —    | 0.4                   | V    |
| V <sub>IH</sub> | Input HIGH Voltage               |                                                             | 2    | V <sub>DD</sub> + 0.3 | V    |
| V <sub>IL</sub> | Input LOW Voltage <sup>(1)</sup> |                                                             | -0.3 | 0.8                   | V    |
| I <sub>LI</sub> | Input Leakage                    | GND ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>                     | -1   | 1                     | μA   |
| I <sub>LO</sub> | Output Leakage                   | GND ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub> , Outputs Disabled | -1   | 1                     | μA   |

**Note:**

1. V<sub>IL</sub> (min.) = -0.3V DC; V<sub>IL</sub> (min.) = -2.0V AC (pulse width < 10 ns). Not 100% tested.  
V<sub>IH</sub> (max.) = V<sub>DD</sub> + 0.3V DC; V<sub>IH</sub> (max.) = V<sub>DD</sub> + 2.0V AC (pulse width < 10 ns). Not 100% tested.

**DC ELECTRICAL CHARACTERISTICS** (Over Operating Range)**V<sub>DD</sub> = 2.4V-3.6V**

| Symbol          | Parameter                        | Test Conditions                                             | Min. | Max.                  | Unit |
|-----------------|----------------------------------|-------------------------------------------------------------|------|-----------------------|------|
| V <sub>OH</sub> | Output HIGH Voltage              | V <sub>DD</sub> = Min., I <sub>OH</sub> = -1.0 mA           | 1.8  | —                     | V    |
| V <sub>OL</sub> | Output LOW Voltage               | V <sub>DD</sub> = Min., I <sub>OL</sub> = 1.0 mA            | —    | 0.4                   | V    |
| V <sub>IH</sub> | Input HIGH Voltage               |                                                             | 2.0  | V <sub>DD</sub> + 0.3 | V    |
| V <sub>IL</sub> | Input LOW Voltage <sup>(1)</sup> |                                                             | -0.3 | 0.8                   | V    |
| I <sub>LI</sub> | Input Leakage                    | GND ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>                     | -1   | 1                     | μA   |
| I <sub>LO</sub> | Output Leakage                   | GND ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub> , Outputs Disabled | -1   | 1                     | μA   |

**Note:**

1. V<sub>IL</sub> (min.) = -0.3V DC; V<sub>IL</sub> (min.) = -2.0V AC (pulse width < 10 ns). Not 100% tested.  
V<sub>IH</sub> (max.) = V<sub>DD</sub> + 0.3V DC; V<sub>IH</sub> (max.) = V<sub>DD</sub> + 2.0V AC (pulse width < 10 ns). Not 100% tested.

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

| Symbol           | Parameter                                        | Test Conditions                                                                                                                          |                     | -8   |      | -10  |      | -20  |      | Unit |
|------------------|--------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------|---------------------|------|------|------|------|------|------|------|
|                  |                                                  |                                                                                                                                          |                     | Min. | Max. | Min. | Max. | Min. | Max. |      |
| I <sub>CC</sub>  | V <sub>DD</sub> Dynamic Operating Supply Current | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>                                                                 | Com.                | —    | 40   | —    | 30   | —    | 25   | mA   |
|                  |                                                  |                                                                                                                                          | Ind.                | —    | 45   | —    | 35   | —    | 30   |      |
|                  |                                                  |                                                                                                                                          | Auto.               | —    | —    | —    | 50   | —    | 45   |      |
|                  |                                                  |                                                                                                                                          | typ. <sup>(2)</sup> | —    | 21   | —    | 21   | —    | —    |      |
| I <sub>CC1</sub> | Operating Supply Current                         | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = 0                                                                                | Com.                | —    | 20   | —    | 20   | —    | 20   | mA   |
|                  |                                                  |                                                                                                                                          | Ind.                | —    | 25   | —    | 25   | —    | 25   |      |
|                  |                                                  |                                                                                                                                          | Auto.               | —    | —    | —    | 40   | —    | 40   |      |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | V <sub>DD</sub> = Max.,<br>V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>CE ≥ V <sub>IH</sub> , f = 0                          | Com.                | —    | 10   | —    | 10   | —    | 10   | mA   |
|                  |                                                  |                                                                                                                                          | Ind.                | —    | 15   | —    | 15   | —    | 15   |      |
|                  |                                                  |                                                                                                                                          | Auto.               | —    | —    | —    | 30   | —    | 30   |      |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | V <sub>DD</sub> = Max.,<br>CE ≥ V <sub>DD</sub> - 0.2V,<br>V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2V, or<br>V <sub>IN</sub> ≤ 0.2V, f = 0 | Com.                | —    | 5    | —    | 5    | —    | 5    | mA   |
|                  |                                                  |                                                                                                                                          | Ind.                | —    | 6    | —    | 6    | —    | 6    |      |
|                  |                                                  |                                                                                                                                          | Auto.               | —    | —    | —    | 15   | —    | 15   |      |
|                  |                                                  |                                                                                                                                          | typ. <sup>(2)</sup> | —    | 1.5  | —    | 1.5  | —    | —    |      |

**Note:**

1. At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.  
2. Typical values are measured at V<sub>DD</sub> = 3.0V, T<sub>A</sub> = 25°C and not 100% tested.

## AC TEST CONDITIONS

| Parameter                                                    | Unit<br>(2.4V-3.6V)   |
|--------------------------------------------------------------|-----------------------|
| Input Pulse Level                                            | 0.4V to $V_{DD}-0.3V$ |
| Input Rise and Fall Times                                    | 1V/ ns                |
| Input and Output Timing<br>and Reference Level ( $V_{Ref}$ ) | $V_{DD}/2$            |
| Output Load                                                  | See Figures 1 and 2   |

## AC TEST LOADS

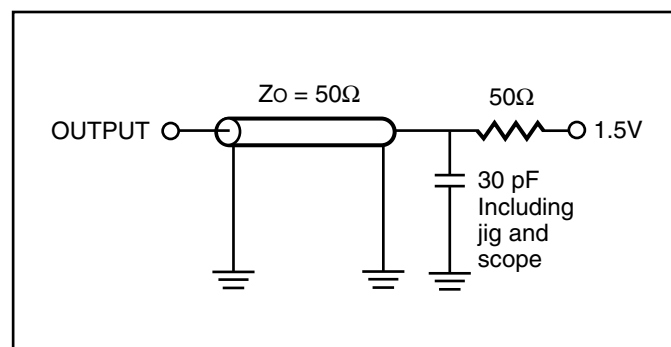


Figure 1.

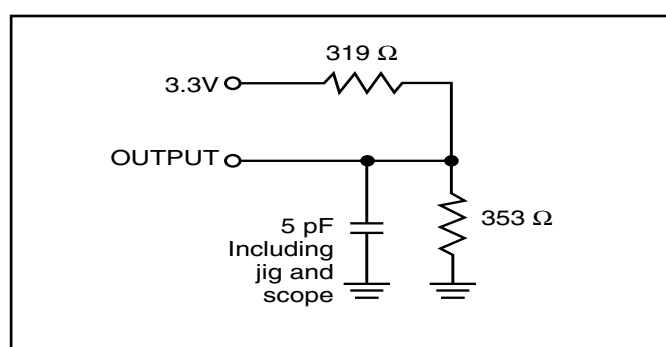


Figure 2.

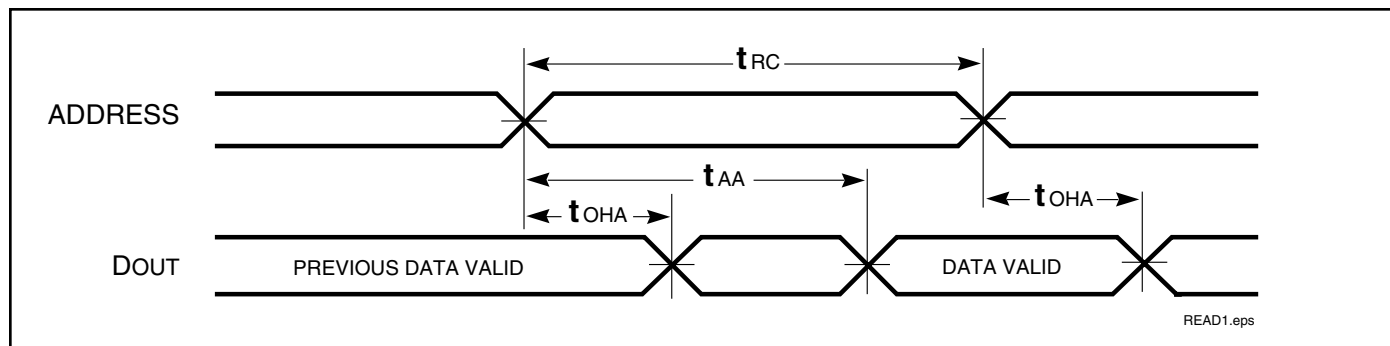
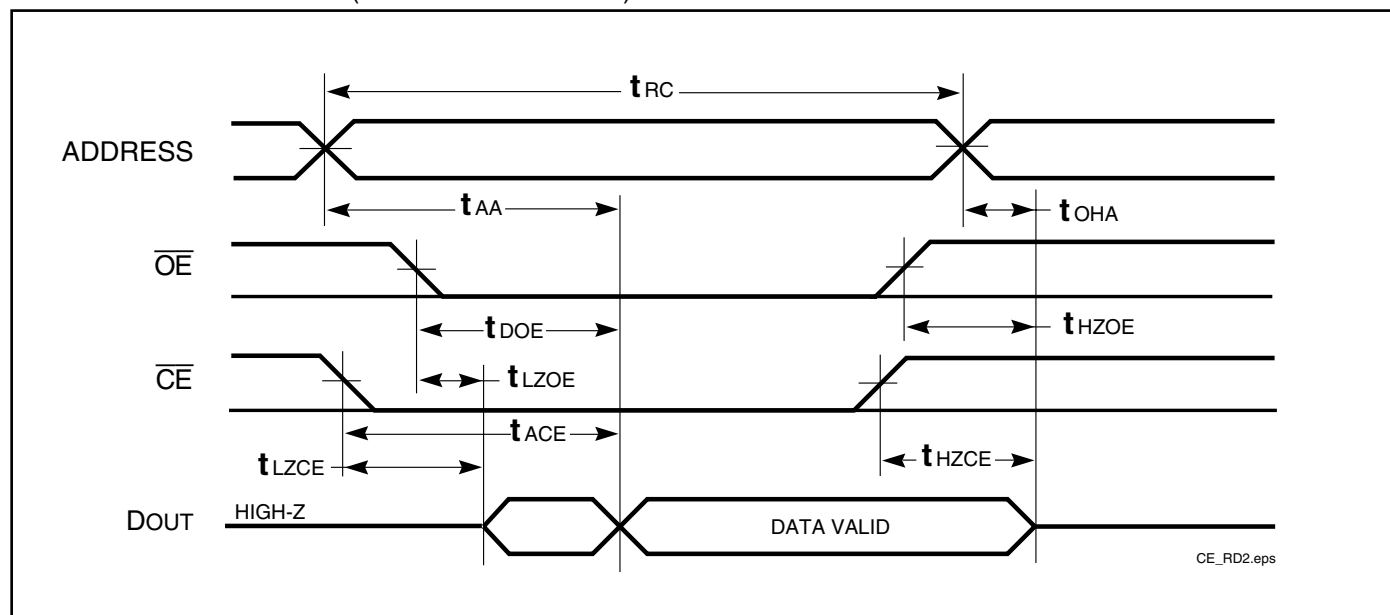
## READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)

| Symbol           | Parameter                        | -8   |      | -10  |      | -20  |      | Unit |
|------------------|----------------------------------|------|------|------|------|------|------|------|
|                  |                                  | Min. | Max. | Min. | Max. | Min. | Max. |      |
| $t_{RC}$         | Read Cycle Time                  | 8    | —    | 10   | —    | 20   | —    | ns   |
| $t_{AA}$         | Address Access Time              | —    | 8    | —    | 10   | —    | 20   | ns   |
| $t_{OHA}$        | Output Hold Time                 | 2.0  | —    | 2.0  | —    | 2.5  | —    | ns   |
| $t_{ACE}$        | $\overline{CE}$ Access Time      | —    | 8    | —    | 10   | —    | 20   | ns   |
| $t_{DOE}$        | $\overline{OE}$ Access Time      | —    | 4.5  | —    | 4.5  | —    | 8    | ns   |
| $t_{HZOE}^{(2)}$ | $\overline{OE}$ to High-Z Output | —    | 3    | —    | 4    | —    | 8    | ns   |
| $t_{LZOE}^{(2)}$ | $\overline{OE}$ to Low-Z Output  | 0    | —    | 0    | —    | 0    | —    | ns   |
| $t_{HZCE}^{(2)}$ | $\overline{CE}$ to High-Z Output | 0    | 3    | 0    | 4    | 0    | 8    | ns   |
| $t_{LZCE}^{(2)}$ | $\overline{CE}$ to Low-Z Output  | 3    | —    | 3    | —    | 3    | —    | ns   |
| $t_{PU}$         | Power Up Time                    | 0    | —    | 0    | —    | 0    | —    | ns   |
| $t_{PD}$         | Power Down Time                  | —    | 8    | —    | 10   | —    | 20   | ns   |

### Notes:

1. Test conditions and output loading conditions are specified in the AC Test Conditions and AC Test Loads (Figure 1).
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage.

## AC WAVEFORMS

READ CYCLE NO. 1<sup>(1,2)</sup> (Address Controlled) ( $\overline{CE} = \overline{OE} = V_{IL}$ )READ CYCLE NO. 2<sup>(1,3)</sup> ( $\overline{CE}$  and  $\overline{OE}$  Controlled)

## Notes:

1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CE} = V_{IL}$ .
3. Address is valid prior to or coincident with  $\overline{CE}$  LOW transitions.

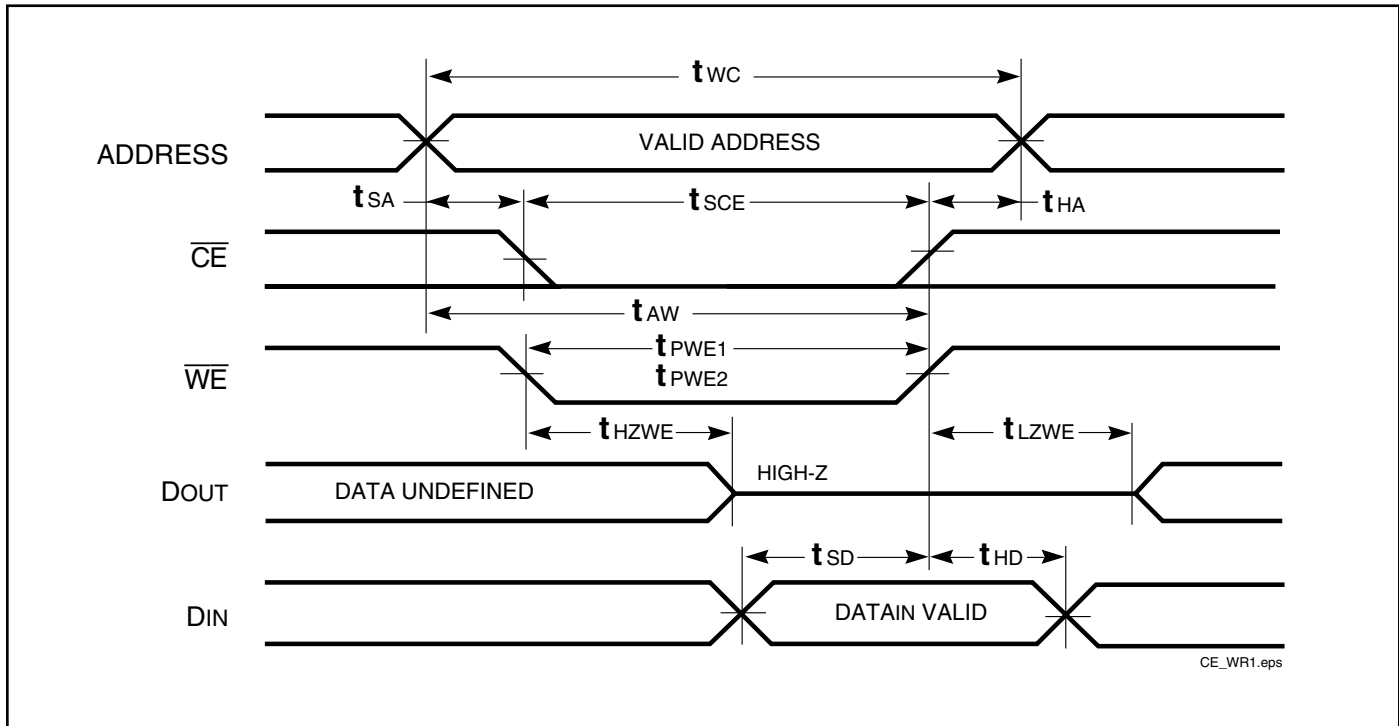
**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,3)</sup>** (Over Operating Range)

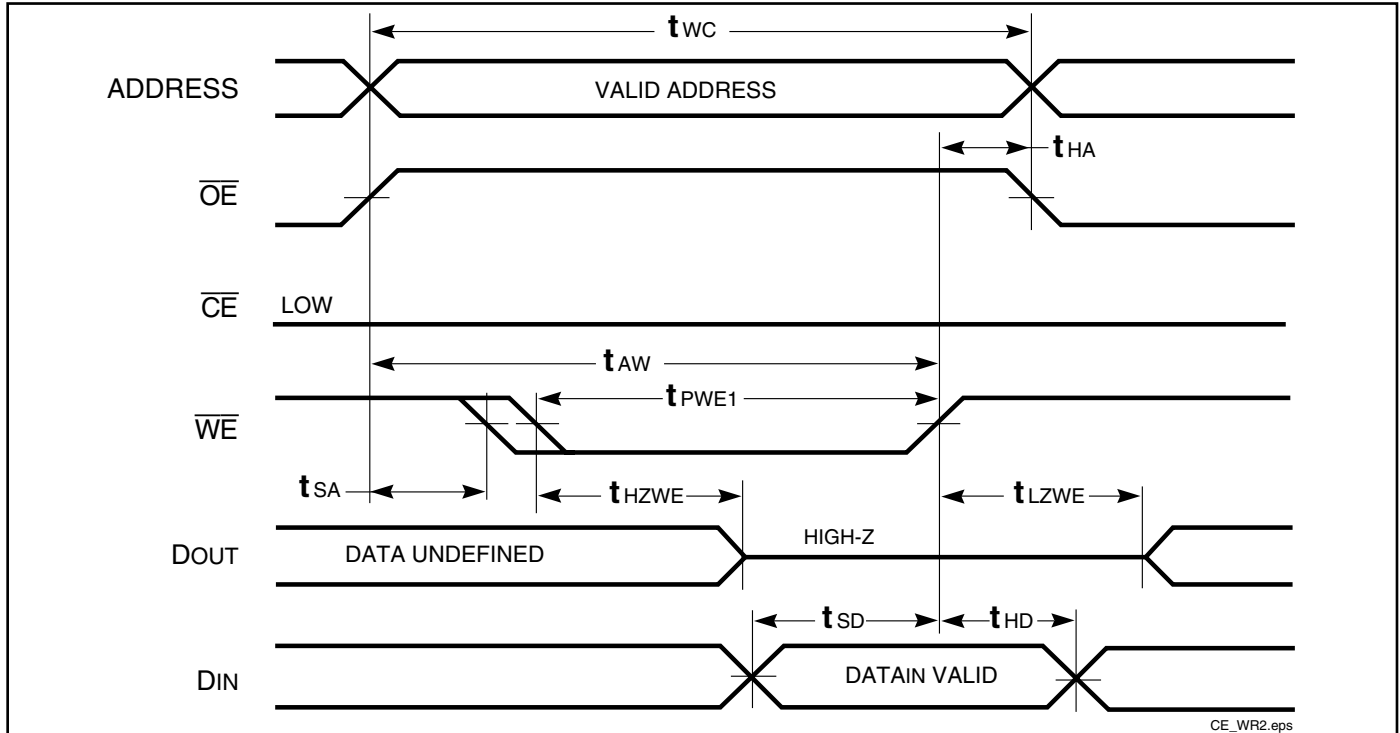
| Symbol                           | Parameter                                            | -8   |      | -10  |      | -20  |      | Unit |
|----------------------------------|------------------------------------------------------|------|------|------|------|------|------|------|
|                                  |                                                      | Min. | Max. | Min. | Max. | Min. | Max. |      |
| t <sub>WC</sub>                  | Write Cycle Time                                     | 8    | —    | 10   | —    | 20   | —    | ns   |
| t <sub>SCE</sub>                 | $\overline{CE}$ to Write End                         | 6.5  | —    | 8    | —    | 12   | —    | ns   |
| t <sub>AW</sub>                  | Address Setup Time to Write End                      | 6.5  | —    | 8    | —    | 12   | —    | ns   |
| t <sub>HA</sub>                  | Address Hold from Write End                          | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>SA</sub>                  | Address Setup Time                                   | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>PWE1</sub>                | $\overline{WE}$ Pulse Width                          | 6.5  | —    | 8    | —    | 12   | —    | ns   |
| t <sub>PWE2</sub>                | $\overline{WE}$ Pulse Width ( $\overline{OE}$ = LOW) | 8.0  | —    | 10   | —    | 17   | —    | ns   |
| t <sub>SD</sub>                  | Data Setup to Write End                              | 5    | —    | 6    | —    | 9    | —    | ns   |
| t <sub>HD</sub>                  | Data Hold from Write End                             | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>HZWE</sub> <sup>(2)</sup> | $\overline{WE}$ LOW to High-Z Output                 | —    | 3.5  | —    | 5    | —    | 9    | ns   |
| t <sub>LZWE</sub> <sup>(2)</sup> | $\overline{WE}$ HIGH to Low-Z Output                 | 2    | —    | 2    | —    | 2    | —    | ns   |

**Notes:**

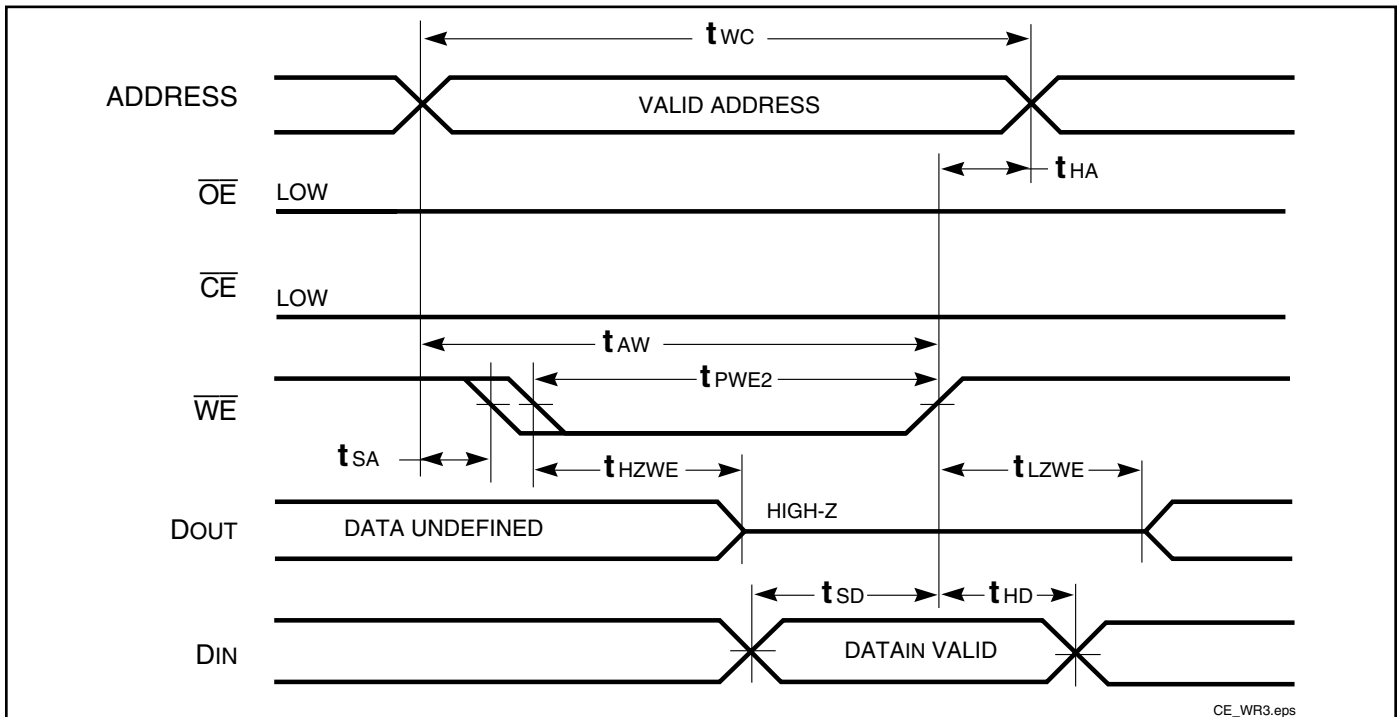
1. Test conditions and output loading conditions are specified in the AC Test Conditions and AC Test Loads (Figure 1).
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of  $\overline{CE}$  LOW, and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write. Shaded area product in development

## AC WAVEFORMS

WRITE CYCLE NO. 1<sup>(1,2)</sup> ( $\overline{CE}$  Controlled,  $\overline{OE}$  = HIGH or LOW)

**WRITE CYCLE NO. 2<sup>(1,2)</sup> ( $\overline{WE}$  Controlled:  $\overline{OE}$  is HIGH During Write Cycle)**

**Notes:**

1. The internal write time is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if  $\overline{OE} > V_{IH}$ .

**WRITE CYCLE NO. 3 ( $\overline{WE}$  Controlled:  $\overline{OE}$  is LOW During Write Cycle)**


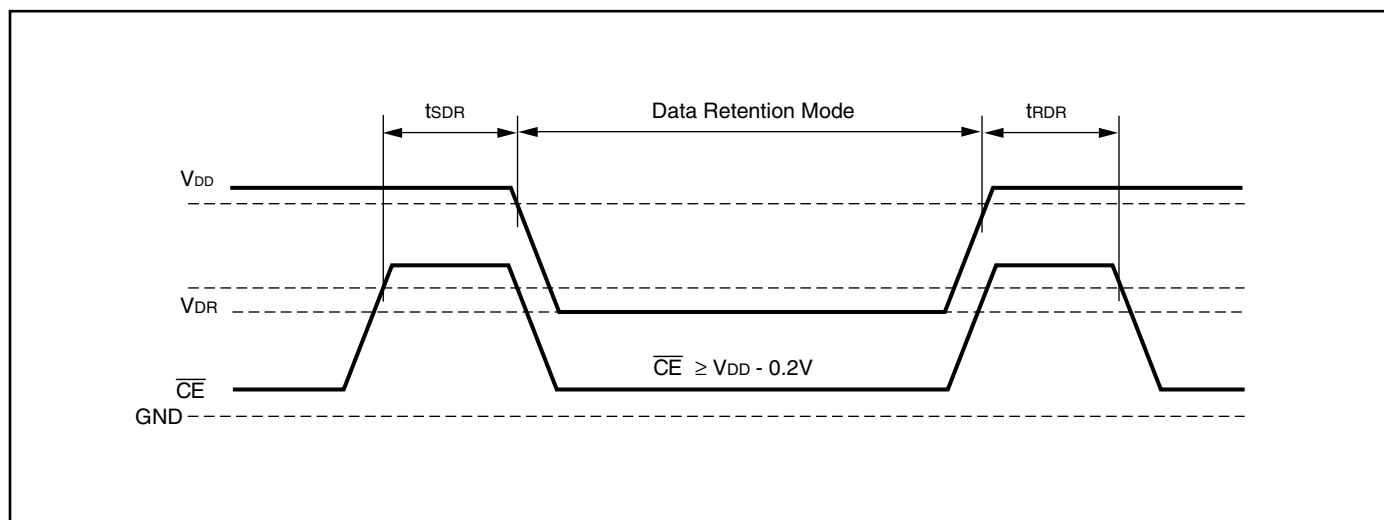
## HIGH SPEED

### DATA RETENTION SWITCHING CHARACTERISTICS (2.4V-3.6V)

| Symbol    | Parameter                   | Test Condition                                       | Options               | Min.        | Typ. <sup>(1)</sup> | Max.         | Unit |
|-----------|-----------------------------|------------------------------------------------------|-----------------------|-------------|---------------------|--------------|------|
| $V_{DR}$  | $V_{DD}$ for Data Retention | See Data Retention Waveform                          |                       | 2.0         | —                   | 3.6          | V    |
| $I_{DR}$  | Data Retention Current      | $V_{DD} = 2.0V$ , $\overline{CE} \geq V_{DD} - 0.2V$ | Com.<br>Ind.<br>Auto. | —<br>—<br>— | 0.5<br>—<br>—       | 5<br>6<br>15 | mA   |
| $t_{SDR}$ | Data Retention Setup Time   | See Data Retention Waveform                          |                       | 0           | —                   | —            | ns   |
| $t_{RDR}$ | Recovery Time               | See Data Retention Waveform                          |                       | $t_{RC}$    | —                   | —            | ns   |

**Note 1:** Typical values are measured at  $V_{DD} = V_{DR}(\min)$ ,  $T_A = 25^\circ\text{C}$  and not 100% tested.

### DATA RETENTION WAVEFORM ( $\overline{CE}$ Controlled)



## ORDERING INFORMATION

### Industrial Range: -40°C to +85°C

| Speed (ns) | Order Part No.       | Package                            |
|------------|----------------------|------------------------------------|
| 8          | IS61WV2568EDBLL-8BLI | 36 mini BGA (6mm x 8mm), Lead-free |
|            | IS61WV2568EDBLL-8TLI | TSOP (Type II), Lead-free          |
|            | IS61WV2568EDBLL-8KLI | 400-mil Plastic SOJ, Lead-free     |

### Industrial Range: -40°C to +85°C

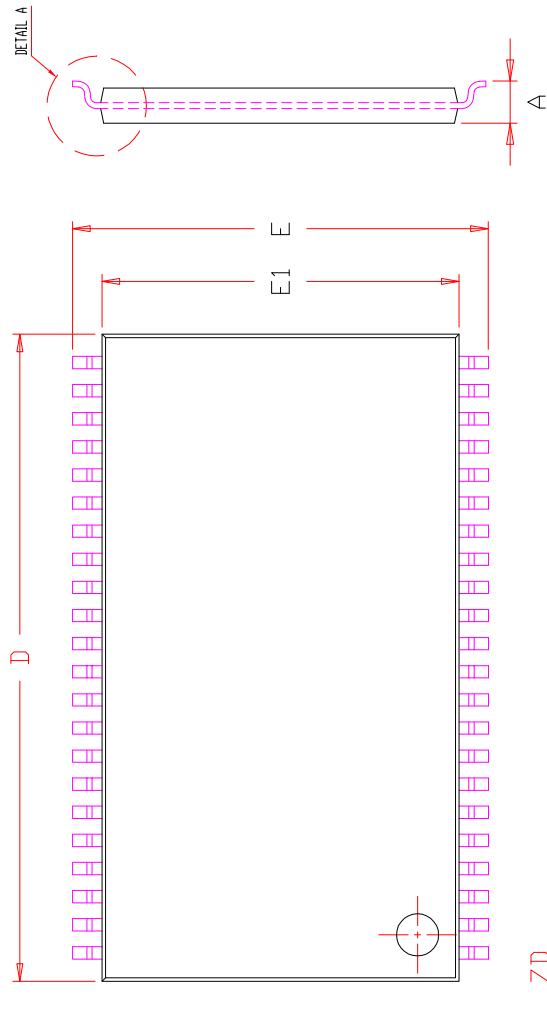
| Speed (ns) | Order Part No.        | Package                            |
|------------|-----------------------|------------------------------------|
| 10         | IS61WV2568EDBLL-10BI  | 36 mini BGA (6mm x 8mm)            |
|            | IS61WV2568EDBLL-10BLI | 36 mini BGA (6mm x 8mm), Lead-free |
|            | IS61WV2568EDBLL-10TI  | TSOP (Type II)                     |
|            | IS61WV2568EDBLL-10TLI | TSOP (Type II), Lead-free          |
|            | IS61WV2568EDBLL-10KLI | 400-mil Plastic SOJ, Lead-free     |

### Automotive (A1) Range: -40°C to +85°C

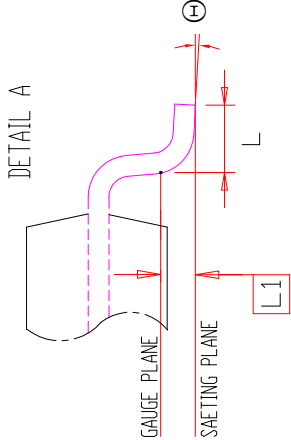
| Speed (ns) | Order Part No.          | Package                                     |
|------------|-------------------------|---------------------------------------------|
| 10         | IS64WV2568EDBLL-10BA1   | 36 mini BGA (6mm x 8mm)                     |
|            | IS64WV2568EDBLL-10BLA1  | 36 mini BGA (6mm x 8mm), Lead-free          |
|            | IS64WV2568EDBLL-10CTA1  | TSOP (Type II), Copper Leadframe            |
|            | IS64WV2568EDBLL-10CTLA1 | TSOP (Type II), Lead-free, Copper Leadframe |
|            | IS64WV2568EDBLL-10KLA1  | 400-mil Plastic SOJ, Lead-free              |

### Automotive (A3) Range: -40°C to +125°C

| Speed (ns) | Order Part No.          | Package                                     |
|------------|-------------------------|---------------------------------------------|
| 10         | IS64WV2568EDBLL-10BA3   | 36 mini BGA (6mm x 8mm)                     |
|            | IS64WV2568EDBLL-10BLA3  | 36 mini BGA (6mm x 8mm), Lead-free          |
|            | IS64WV2568EDBLL-10CTA3  | TSOP (Type II), Copper Leadframe            |
|            | IS64WV2568EDBLL-10CTLA3 | TSOP (Type II), Lead-free, Copper Leadframe |
|            | IS64WV2568EDBLL-10KLA3  | 400-mil Plastic SOJ, Lead-free              |



| SYMBOL | DIMENSION IN MM |       |       | DIMENSION IN INCH |       |       |
|--------|-----------------|-------|-------|-------------------|-------|-------|
|        | MIN.            | NOM.  | MAX.  | MIN.              | NOM.  | MAX.  |
| A      | 1.00            |       | 1.20  | 0.039             |       | 0.047 |
| A1     | 0.05            |       | 0.15  | 0.002             |       | 0.006 |
| A2     | 0.95            | 1.00  | 1.05  | 0.037             | 0.039 | 0.041 |
| b      | 0.30            |       | 0.45  | 0.012             |       | 0.018 |
| D      | 18.28           | 18.41 | 18.54 | 0.720             | 0.725 | 0.730 |
| E      | 11.56           | 11.76 | 11.96 | 0.455             | 0.463 | 0.471 |
| E1     | 10.03           | 10.16 | 10.29 | 0.395             | 0.400 | 0.405 |
| e      | 0.80            | BSC.  |       | 0.031             | BSC.  |       |
| L      | 0.40            |       | 0.69  | 0.016             |       | 0.027 |
| L1     | 0.25            | BSC.  |       | 0.010             | BSC.  |       |
| ZD     | 0.805           | REF.  |       | 0.032             | REF.  |       |
| Θ      | 0               |       | 8°    | 0                 |       | 8°    |



NOTE :

- 1. CONTROLLING DIMENSION : MM
- 2. DIMENSION D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.



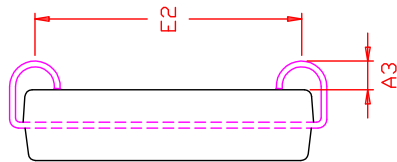
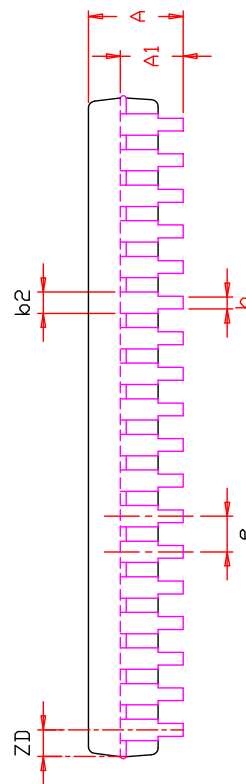
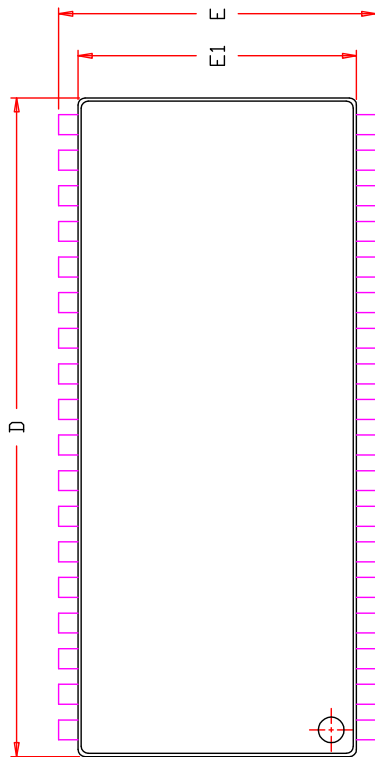
44L 400mil TSOP-2  
Package Outline

F

REV.

DATE

06/04/2008



| SYMBOL | DIMENSION IN MM |       | DIMENSION IN INCH |       |
|--------|-----------------|-------|-------------------|-------|
|        | MIN.            | MAX.  | MIN.              | MAX.  |
| A      | 3.25            | 3.76  | 0.128             | 0.148 |
| A1     | 2.08            |       | 0.082             |       |
| A3     | 0.635           |       | 0.025             |       |
| b      | 0.38            | 0.51  | 0.015             | 0.020 |
| b2     | 0.66            | 0.71  | 0.026             | 0.028 |
| D      | 23.36           | 23.49 | 0.920             | 0.925 |
| E      | 11.05           | 11.18 | 0.435             | 0.440 |
| E1     | 10.03           | 10.16 | 0.395             | 0.400 |
| E2     | 9.40            | BSC.  | 0.370             | BSC.  |
| e      | 1.27            | BSC.  | 0.050             | BSC.  |
| ZD     | 0.95            | REF.  | 0.037             | REF.  |

## NOTE :

1. Controlling dimension : mm
2. Dimension D and E1 do not include mold protrusion .
3. Dimension b2 does not include dambar protrusion/intrusion.
4. Formed leads shall be planar with respect to one another within 0.1mm at the seating plane after final test.
5. Reference document : JEDEC SPEC MS-027.



**TITLE**

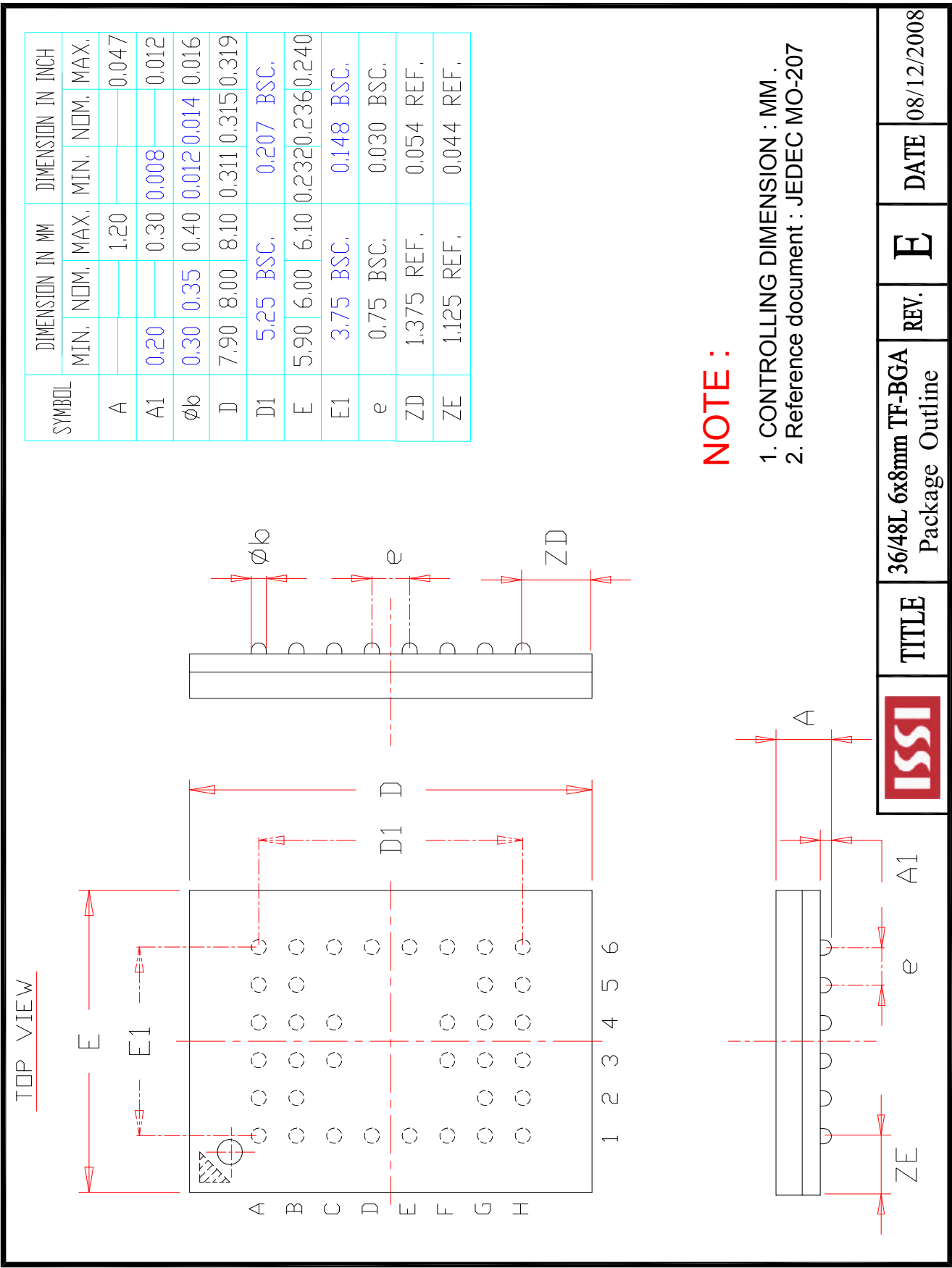
**36L 400mil SOJ  
Package Outline**

**REV.**

**F**

**DATE**

**12/20/2007**



Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)

[www.lifeelectronics.ru](http://www.lifeelectronics.ru)